

CONFIDENTIAL REPORTED AT YO ADVINCED MEDIO DEVICES INC.

TOOR Advanced from Devices (a) to the uniche property of Monport of the provided only to entitles uniche a property of Monand is provided only to entitles uniche a non-declouse separate
with AMD for endering propose. First develocition or declouses
after the sendantic reports. Service develocition or declouses
after the sendantic reports. Service develocition or declouses
and the AMD. AMD reads no expression of the sendantic reports.

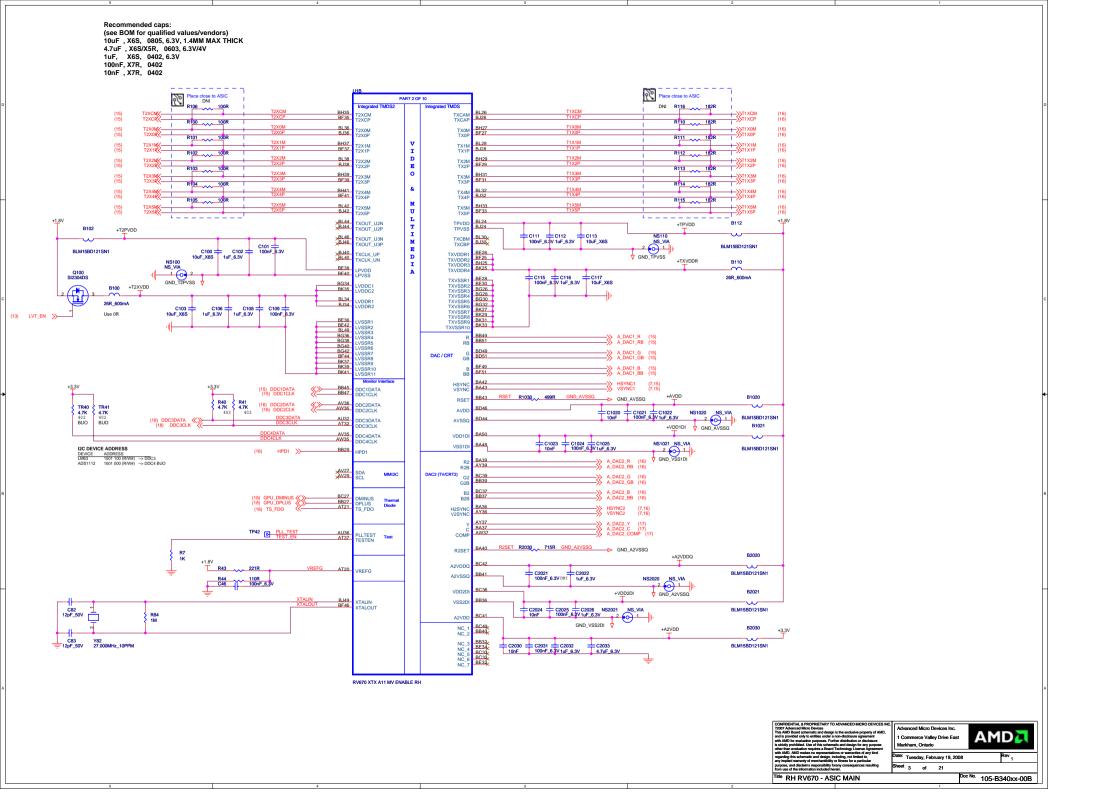
If Commercial Valley Drive East
Markham, Ornizóro

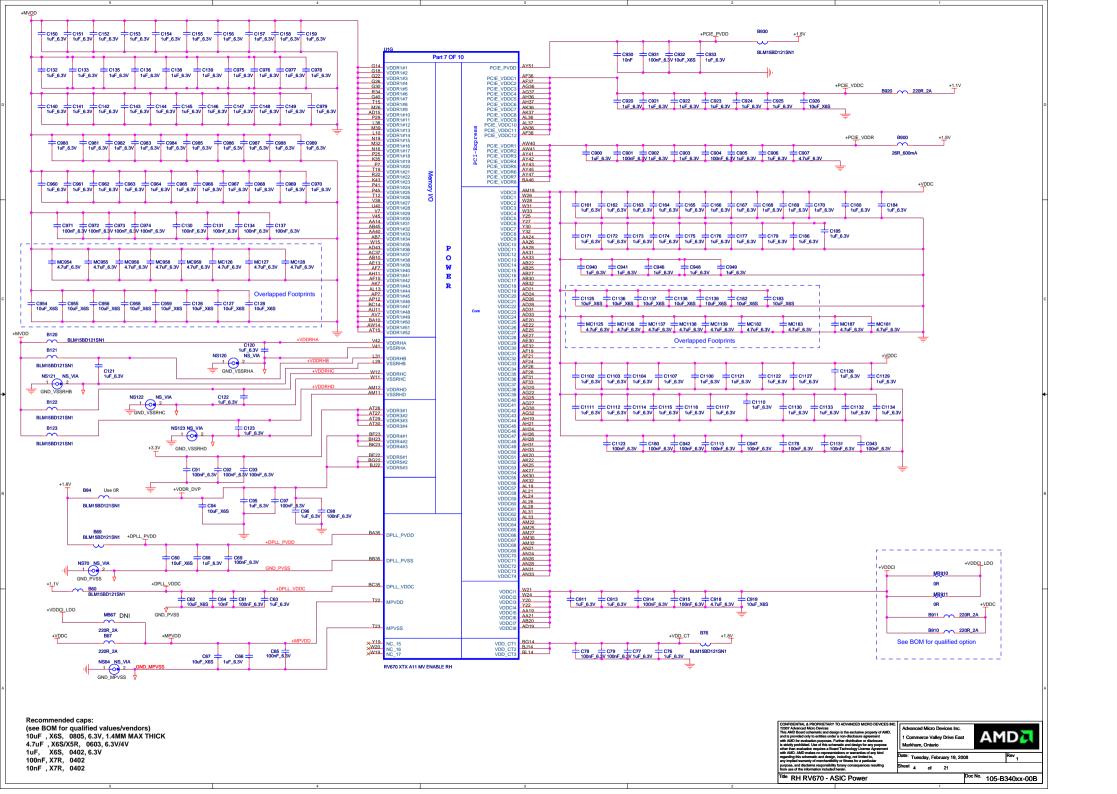
Delit: Tuceday, February 19, 2008

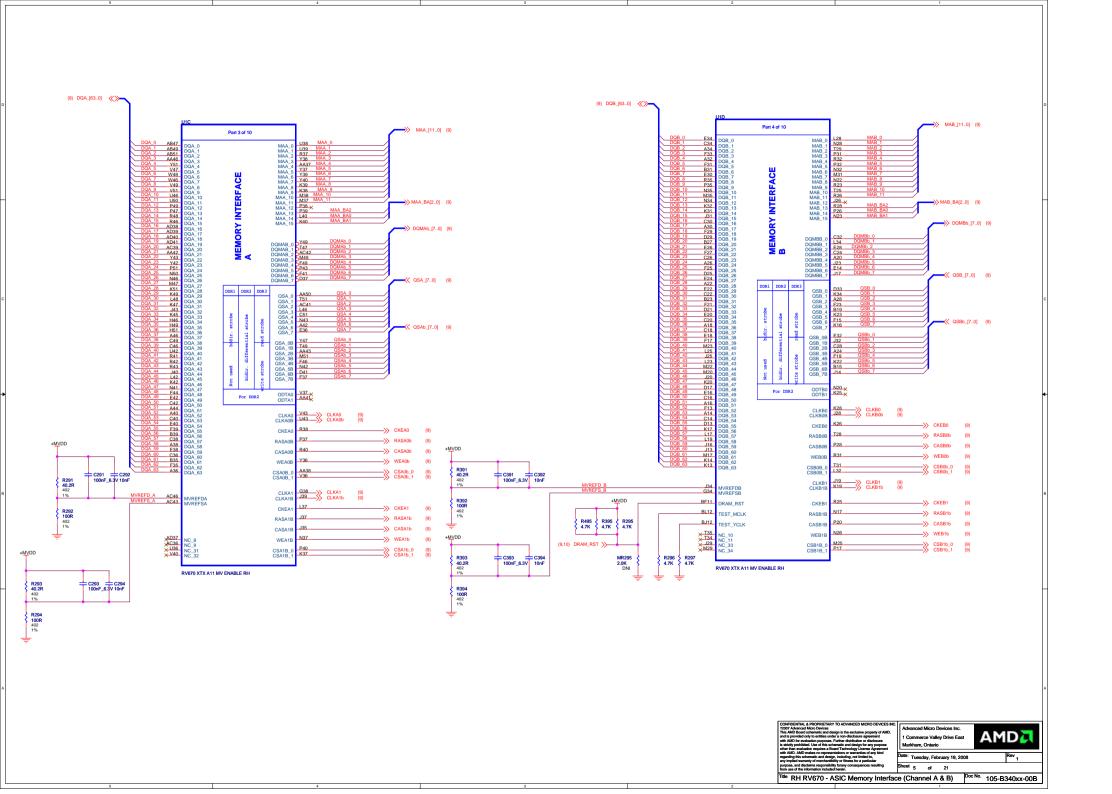
Rev 1

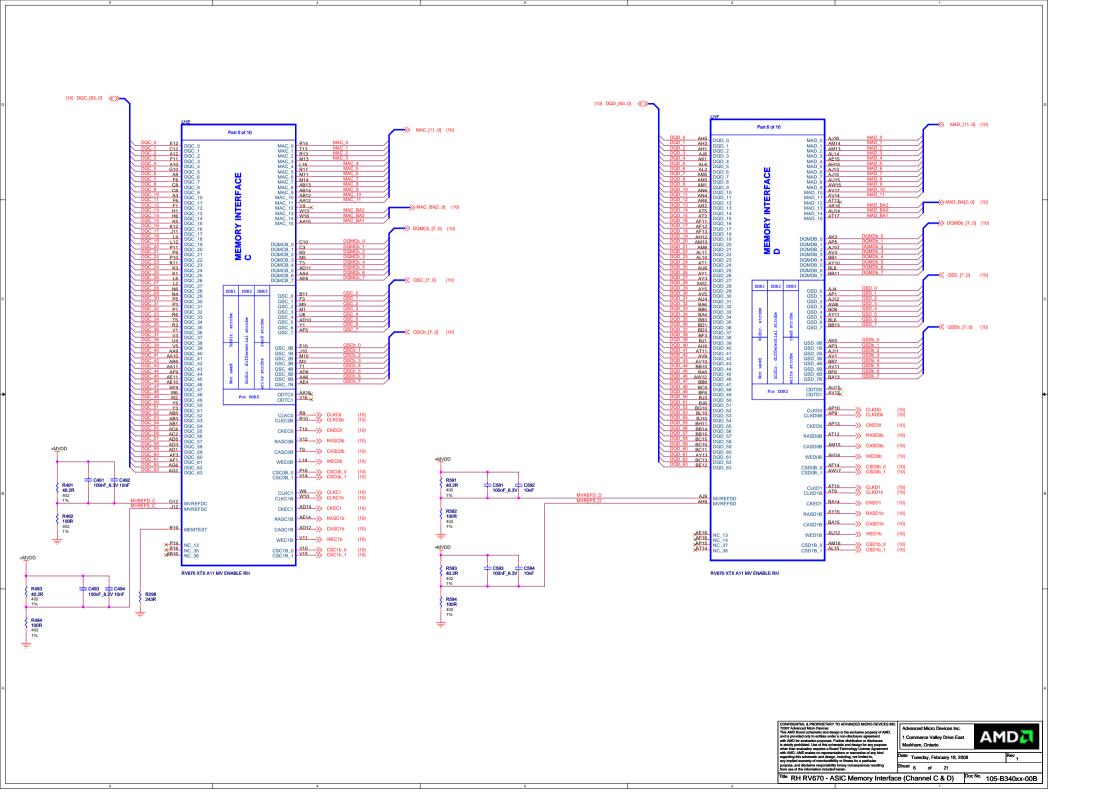
Title RH RVG70 - ASIC PCIE_Interface

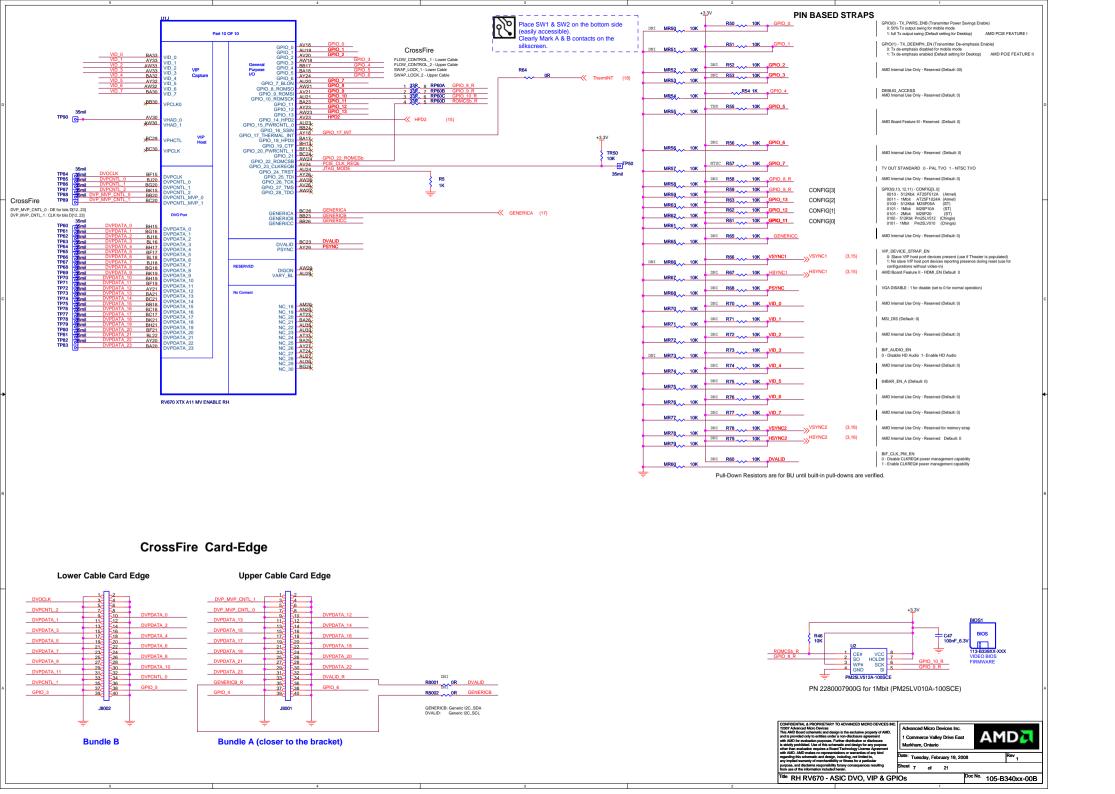
Doc No. 105-B34(0xx-00B)

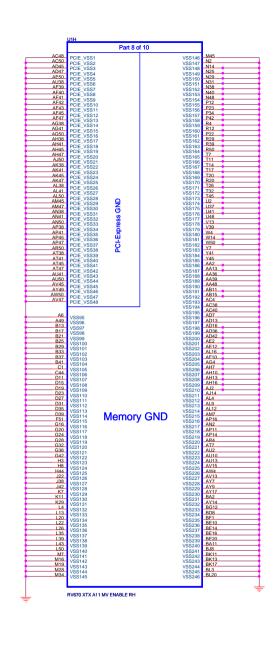


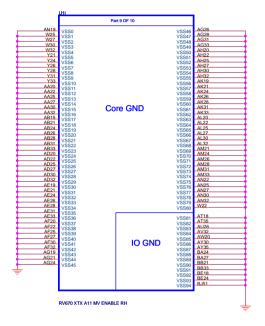








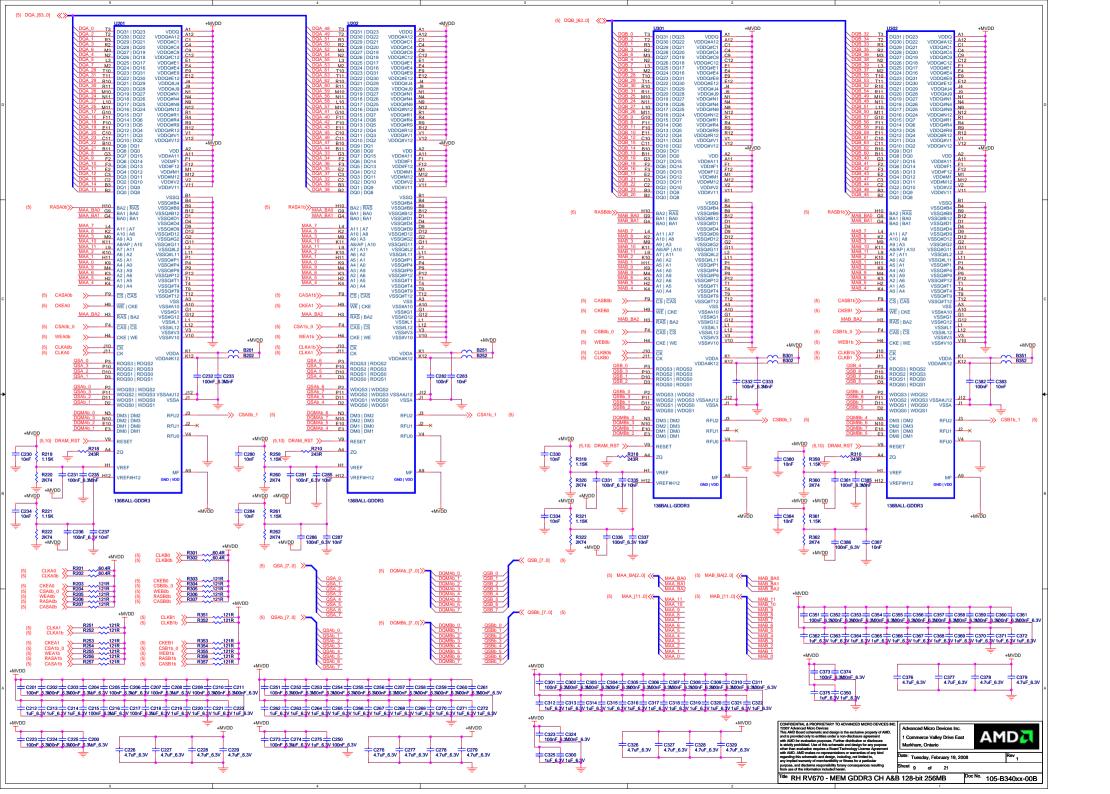


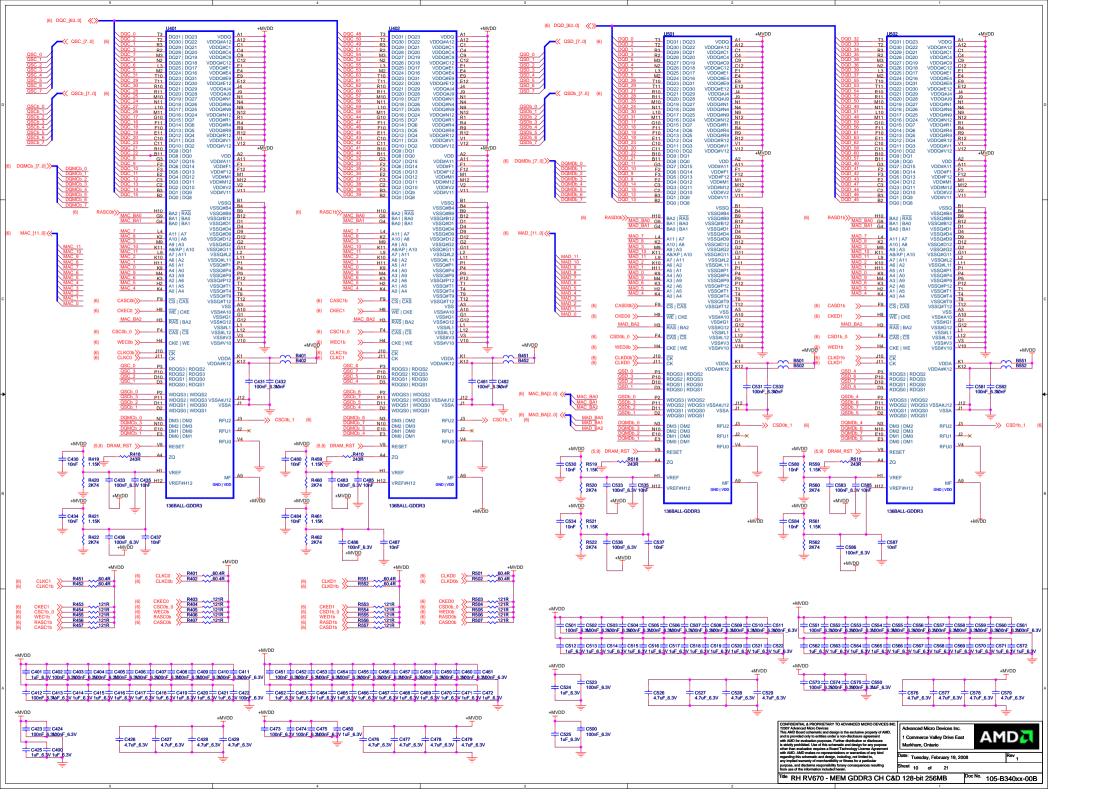


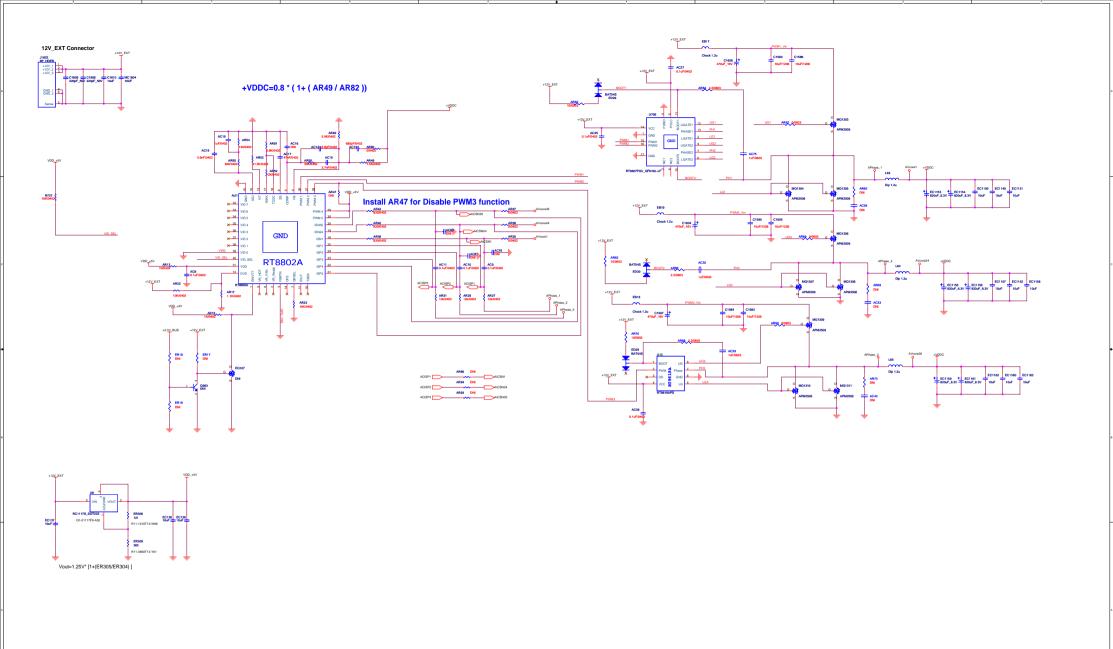
CONTROLLA & PROPRIETARY TO ADVINCED MICHO DEVICES INC.

2007 Advanced Micro Devices inc.

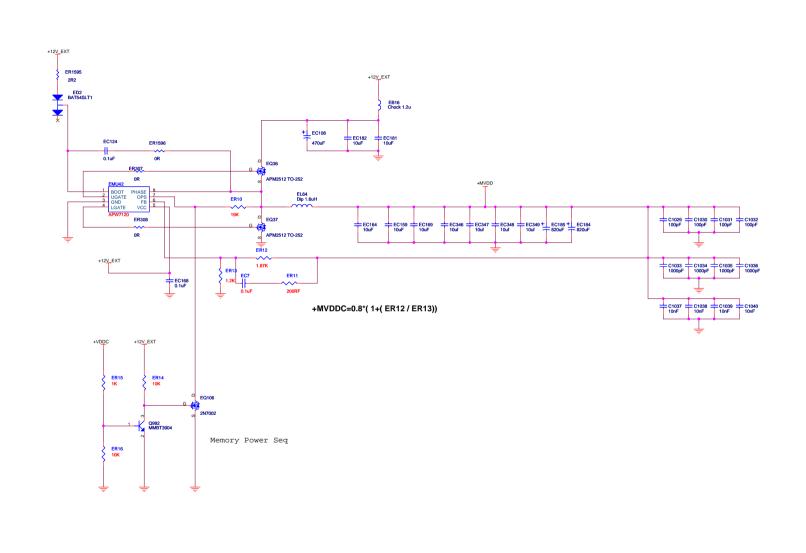
The AND Deard otherwise and design in the exclusion propriety of AND, visit and AND the control proprietary of AND, visit and AND for exclusion propriets. First deviation or deductions in a most proteint of the of the information of develope for any propriets with AND. AND control in operaturations or compressations or compressations or control and any propriet secretly of machine things or these for a particular propriet, and deduction responsibly for the propriets. The analysis of the analysis



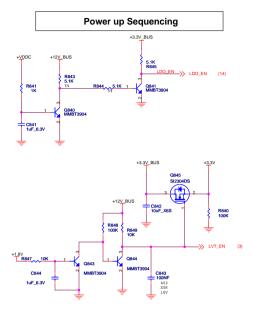








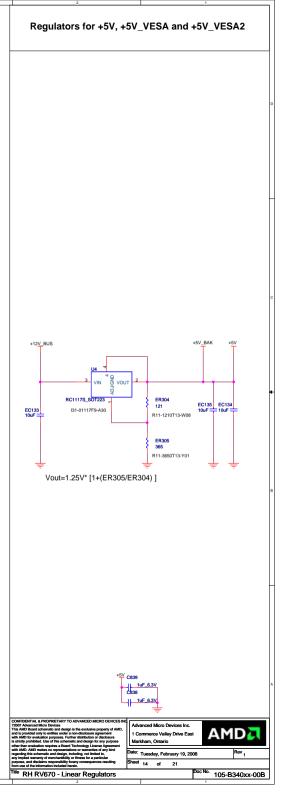
COMPRIENTIAL & PROPERTANT TO ADVANCED MACTO DEVICES MCT.
This ALM State of intensities and design is the suchearing person of the suchearing person of the such perso

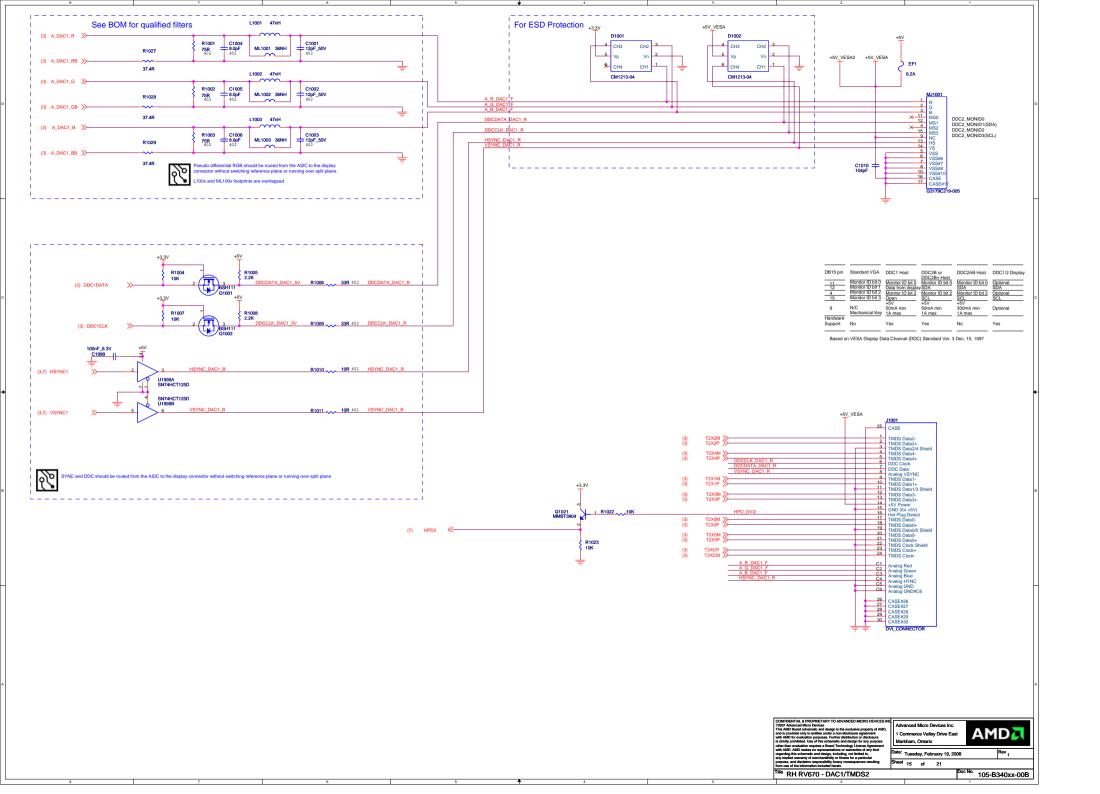


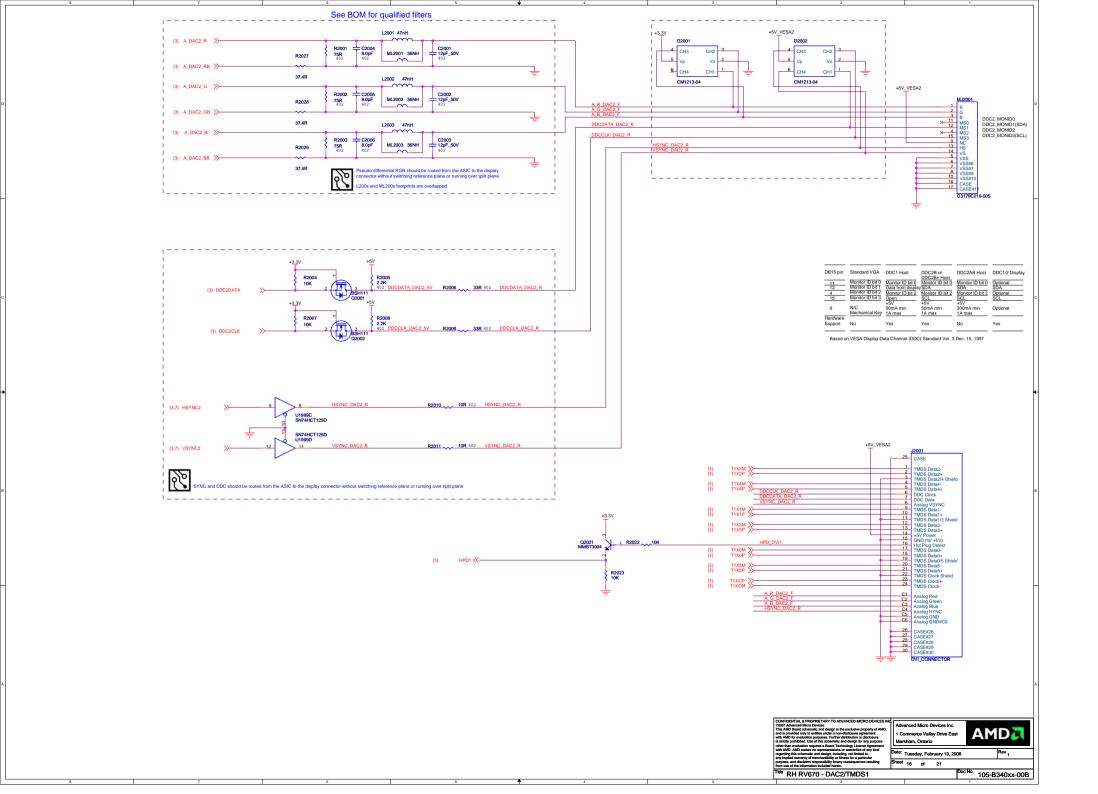


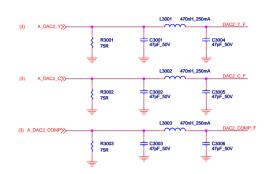
LDO #2: Vin = 2.5V to 3.6V MAX Vout = +1.8V +/- 3% lout = 0.8A (TBV) RMS MAX PCB: 50 to 70mm sq. copper area for cooling R868 Overlap footprints C865 33pF_50V R5 VOUT = Vref x (1 + R5/R4)LDO #3: Vin = +1.70V to 2.1VMAX Vout = +1.1V +/- 3% lout = Up to 1.3A (TBV) RMS MAX PCB: 50 to 70mm sq. copper area for cooling Overlap footprints R858 R855 C855 33pF_50V R5 R854 R4 VOUT = Vref x (1 + R5/R4)LDO #6: For fixed output voltage: Vin = +1.70V to 2.1V MAX Vout = +1.20V +/- 3% lout = 1.3A (TBV) RMS MAX PCB: 50 to 70mm sq. copper area for cooling LDO #6: For tracking VDDC: Vin = TBD Vout = TBD lout = 1.3A (TBV) RMS MAX PCB: 50 to 70mm sq. copper area for cooling Overlap footprints C872 C871 10uF_X6S C874 100nF_6.3V R5 C3 R874 R4 1R_1210 VOUT = Vref x (1 + R5/R4)1/2W each 1/2W 1210 P872 - R876 □ NR878 can share pad with MR878. DNI OR 1R_1210 1R 1210 One of them must be installed Add large copper area under R870~R873 for heat dissipation (~2W).

TBD



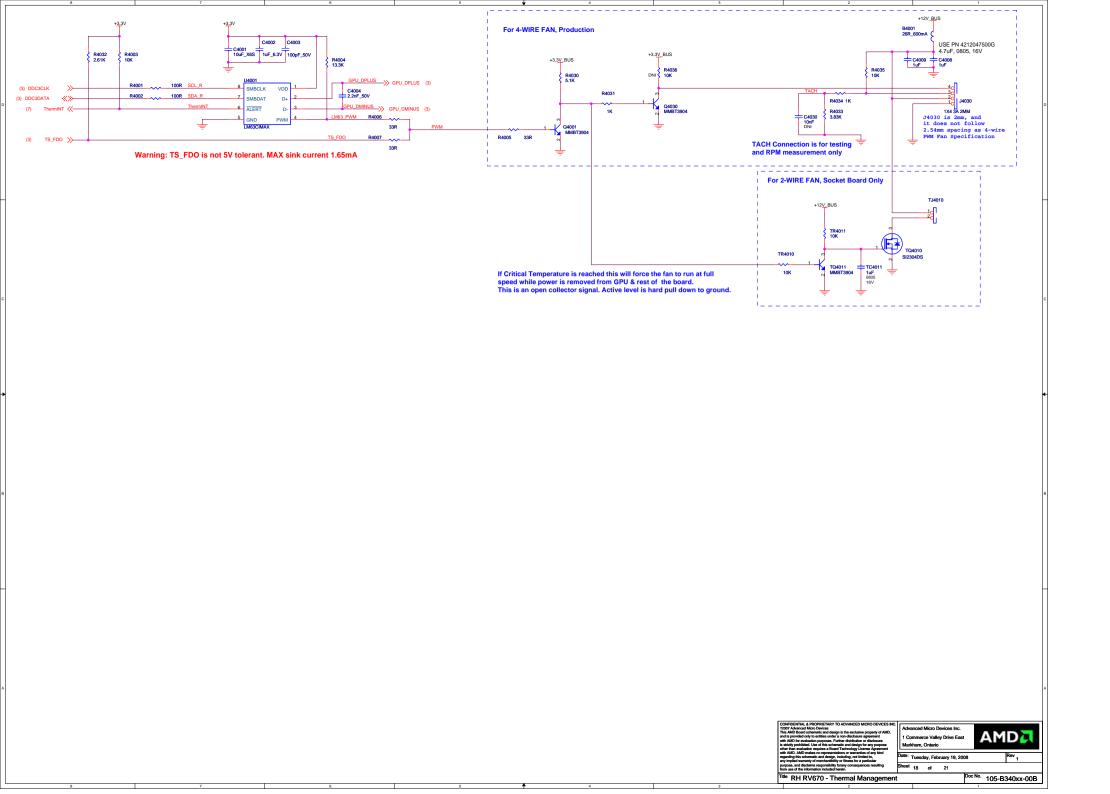


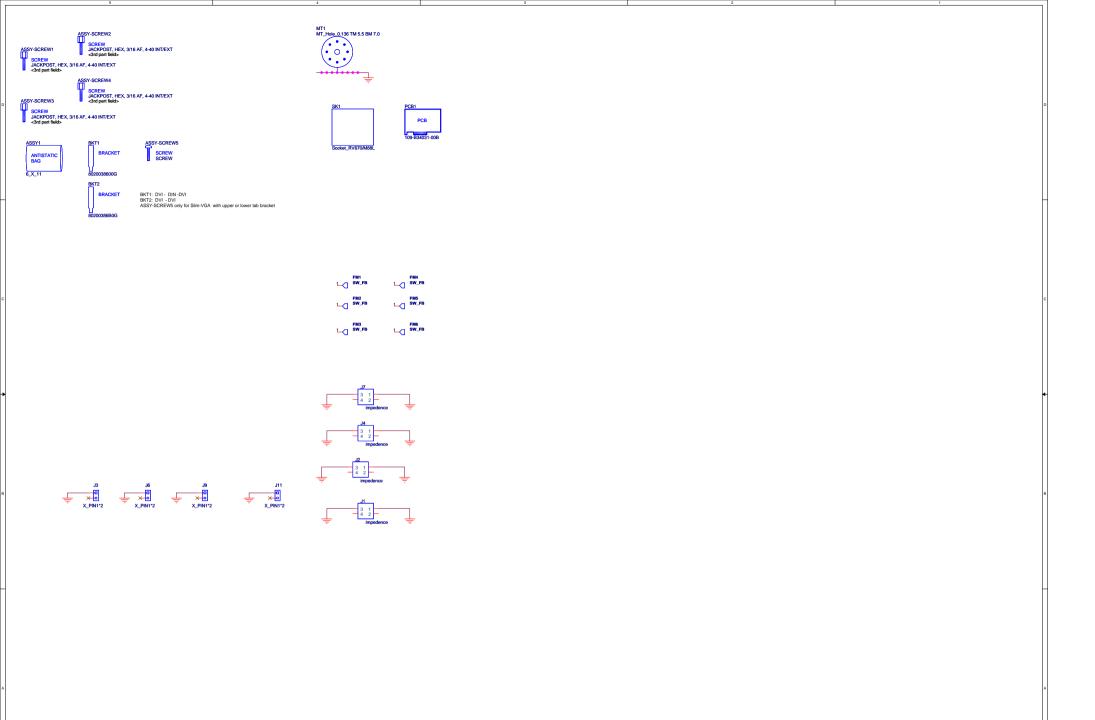






CONTRICEMUL & PROPRIETAY TO ACHNOCED MICROS PACKES INC.
TOTAL ARROPMENT AND THE ACHNOCED PACKES INC.
TOTAL ARRO





COMPEDITURA PROPRETARY TO ADVANCED MICRO ENCISES NC.
TOTAL Absence Micro Devices in Proceedings of the continue program of the enables program of the mediate meganically interest to a particular program of the mediate meganically interest to a particular program of the mediate meganically interest to a particular program of the mediate meganically interest to a particular program of the mediate meganically interest to a particular program of the mediate meganically interest to a particular program of the mediate meganically interest to a particular program of the mediate program of the medi

	Δ	МГ	5	Title RH PCIE RV670 512MB GDDR3 DUAL DL-DVI-I VO F	TH	Schematic No. 105-B340xx-00B	Date: Tuesday, February	y 19, 2008	
AMD			REVISION HISTORY	For Stuffing options (cor	nts the PCB, it does not represent any specific SKU. Imponent values, DNI ,? please consult the product specific BOM. Intersentative to obtain latest BOM closest to the application desired.				
	Sch Rev	PCB Rev	Date	R	REVISION DESCRIPTION				
	0	00A	07/05/11	Initial design for RV670 GDDR3 (Revival) based on B339					
	1	00в	07/08/1	(pg 1) Adding R1 and connecting switch #7 of TSW1. Some mother boards require B7 to be grounded. Table-1 updated accordingly (pg 7) Adding R64 and MR64 to select HOT_PLUG_DET or ThermINT as the interrupt source. (pg 13) Adding R1617, MR1617, R1616, Q1613, R1615, R1618, and R1619 as option to support hot plug detection of external cable. (pg 13) Adding R1282, MR1282, R1283, MR1283, R1284, MR1284, R1281, R1285, Q1280, and C1280 as option for thermal protection for VDDC SMPS MOSFETs (pg 13) Adding MC1603 (overlapped with C1603) (pg 14) Adding D870 as option for power up sequencing (pg 18) Adding heatsink symbol/footprint (Layout) Increasing spacing between DDC4DATA & DDC4CLK going to U1270 to reduce the crosstalk					
0									
В									
A									
			5	4	3	T 2		1	

evana

